

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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# 1SS86

Silicon Schottky Barrier Diode for UHF TV Tuner Mixer

**RENESAS**

ADE-208-186B (Z)

Rev. 2  
Oct. 2000

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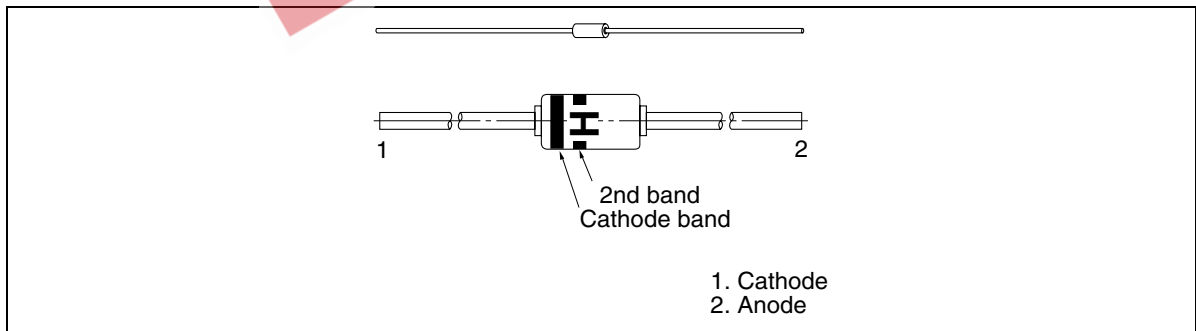
## Features

- Low capacitance. (C = 0.85 pF max)
- High reliability with glass seal.

## Ordering Information

Type No.	Cathode band	2nd band	Mark	Package Code
1SS86	White	White	H	DO-35

## Pin Arrangement



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## 1SS86

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### Absolute Maximum Ratings

(T<sub>a</sub> = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	3	V
Average forward current	I <sub>o</sub>	30	mA
Power dissipation	Pd	150	mW
Junction temperature	T <sub>j</sub>	100	°C
Storage temperature	Tstg	-55 to +100	°C

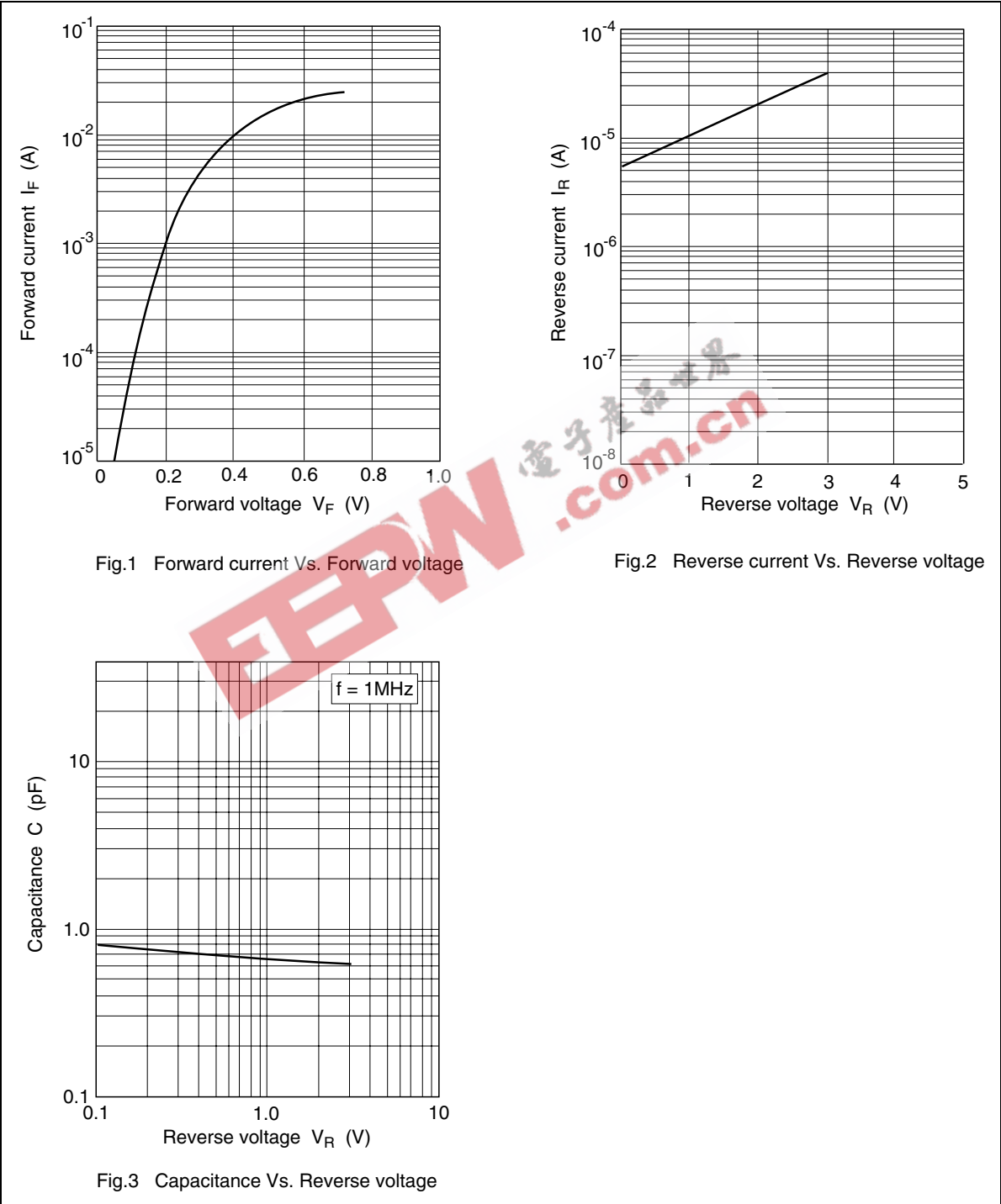
### Electrical Characteristics

(T<sub>a</sub> = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward current	I <sub>F</sub>	8	—	—	mA	V <sub>F</sub> = 0.5 V
Reverse voltage	V <sub>R</sub>	3	—	—	V	I <sub>R</sub> = 1 mA
Reverse current	I <sub>R</sub>	—	—	50	μA	V <sub>R</sub> = 0.5 V
Capacitance	C	—	—	0.85	pF	V <sub>R</sub> = 0.5 V, f = 1 MHz
ESD-Capability *	—	30	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

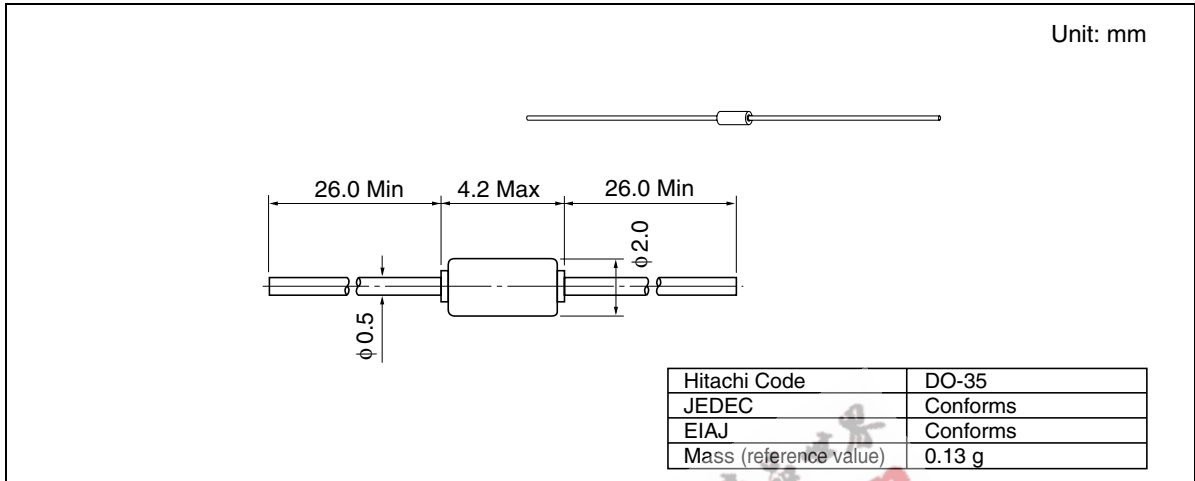
Note: Failure criterion ; I<sub>R</sub> > 50 μA at V<sub>R</sub> = 0.5 V

Main Characteristic



# 1SS86

## Package Dimensions



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